

REMARKS

Claims 1-27 are pending. By this Amendment, claims 1-5 and 21-23 are amended.
No new matter has been added.

The amendments to claims are supported, for example, on page 21, line 15-page 22, line 2 of the specification.

Applicants thank Examiner Fourson for the courtesies extended to Applicants' representative during the February 11, 2004 personal interview. The points and agreements are incorporated into the remarks below and constitute the Applicants' record of the interview.

For the following reasons, Applicants submit that this application is allowable.
Reconsideration of the present application is respectfully requested.

I. The Claims Define Allowable Subject Matter

On page 2 of the Office Action, claims 1-27 are rejected under 35 U.S.C. §112, first paragraph for allegedly failing to comply with the written description requirement. Claims 1, 2, and 21 are amended to obviate the rejection by reciting a features supported, for example on page 21, line 15-page 22, line 2 of the specification.

Regarding claims 8-10, Applicants respectfully submit that the claims are fully described and supported on page 36, lines 7-18, where a third transfer layer (thin film device layer) is disclosed to be electrically connected to the other layers.

Withdrawal of the rejection is respectfully requested as it was agreed at the interview the amendments overcome the rejection.

On page 2 of the Office Action, claims 1-7 and 11-27 are rejected under 35 U.S.C. §103(a) over U.S. Patent No. 5,087,585 to Hayashi in view of U.S. Patent No. 5,499,124 to Vu et al. ("Vu"). This rejection is respectfully traversed.

As agreed during the February 11, 2004 interview, none of Hayashi, Vu, nor their combination disclose or suggest ablation in at least one of the separable layer and at an interface, as recited in claims 1 and 21, or ablation in a separable layer, as recited in claim 2.

Hayashi discloses removal of the substrate by selective polishing the substrate in column 3, lines 37-40. Hayashi fails to disclose or suggest ablation.

Vu fails overcome the deficiencies in Hayashi because Vu also fails to disclose or suggest ablation. Vu merely discloses that the SI circuits are diced by being divided into dice or tiles containing one or more circuits, which are sequentially registered onto a common module body, and sequentially adhered to the module body (col. 2, lines 49-55). In Figures 4h and 5a of Vu, the substrate 30 is shown to be removed, but fails to disclose how the substrate 30 is removed.

Further, the alternative embodiment of Vu discussed during the interview also fails to disclose ablation. In the alternative embodiment of Vu, the circuit tiles are registered, and adhered to the module body 110 and the transfer body 80, and the epoxy 82 is removed by exposure to UV radiation which diminishes or removes the adhesive properties of the selective adhesive 82, allowing the glass (transfer body) 80 to be lifted off (col. 6, lines 41-46).

It is noted that in Vu, the adhesive properties of the selected adhesive 82, which is an epoxy, is either diminished or removed, which implies that the entire epoxy 82 undergoes a property change which is distinguishable from the specific meaning of ablation. As disclosed in page 21 of the specification, ablation is defined as occurring when a solid material, which has absorbed light, is photo-chemically or thermally excited, and interatomic or intermolecular bonds on the surface or in the interior of the separable layer are broken and evolved.

Based on this definition, it was agreed that neither Hayashi nor Vu disclose ablation.

For at least these reasons, it is respectfully submitted that claims 1, 2 and 21 are patentable over the applied references. The dependent claims are likewise patentable over the applied references for at least the reasons discussed as well as for the additional features they recite. Applicants respectfully request that the rejection under 35 U.S.C. 103 be withdrawn.

II. Conclusion

In view of the foregoing, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt allowance are earnestly solicited.

Should the Examiner believe anything further is desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicants' undersigned representative at the telephone number listed below.

Respectfully submitted,



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Date: March 1, 2004

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